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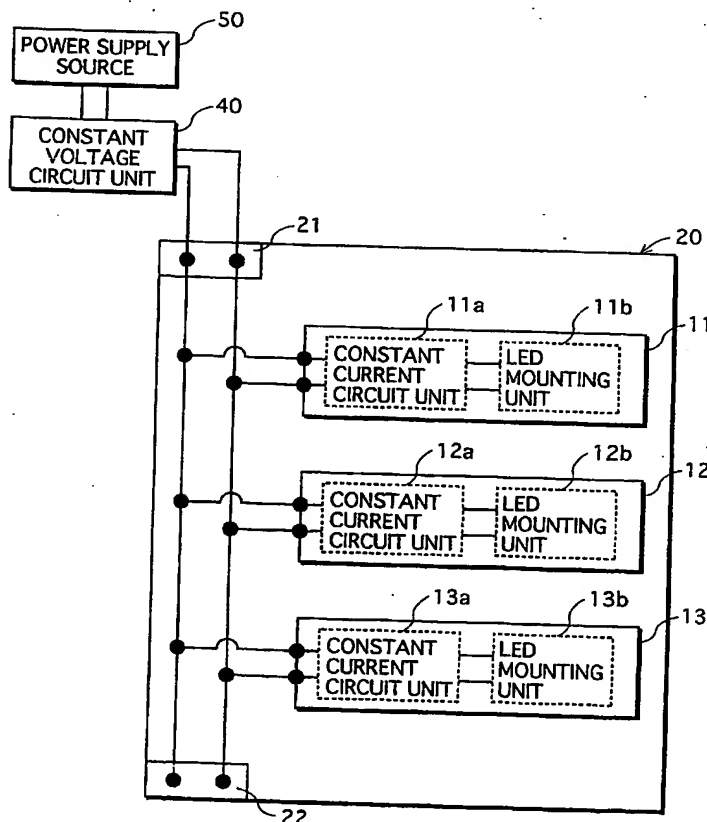
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(21) International Application Number: PCT/JP2003/016428 (75) Inventors/Applicants (for US only): SETOMOTO, Tatsumi [JP/JP]; AlubaTakatsuki 403, Kamihamuro, Takatsuki-shi, Osaka 569-1044 (JP). MATSUI, Nobuyuki [JP/JP]; 1-44-9-A401, Tsunoe-cho, Takatsuki-shi, Osaka 569-0822 (JP). TAMURA, Tetsushi [JP/JP]; 2-8-509, Saiwai-cho, Takatsuki-shi, Osaka 569-1143 (JP). TANI-MOTO, Noriyasu [JP/JP]; 2-8-401, Saiwai-cho, Takatsuki-shi, Osaka 569-1143 (JP). SHIMIZU, Masanori [JP/JP]; 48-3-4-618, Mibuboujo-cho, Nakagyo-ku, Kyoto-shi, Kyoto 604-8804 (JP).
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(74) Agent: NAKAJIMA, Shiro; 6F, Yodogawa 5-Bankan, 2-1, Toyosaki 3-chome, Kita-ku, Osaka-shi, Osaka 531-0072 (JP).
(71) Applicant (for all designated States except US): MAT-SUSHITA ELECTRIC INDUSTRIAL CO., LTD. [JP/JP]; 1006, Oazakadoma, Kadoma-shi, Osaka 571-8501 (JP).
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(54) Title: MULTICHIP LED LIGHTING DEVICE



(57) Abstract: In a module socket, a connector and a connector are connected by wiring, and three LED modules are connected in parallel with respect to a constant voltage circuit unit via the wiring. Each module has a constant current circuit unit and an LED mounting unit. The constant current circuit unit includes one resistor and two transistors mounted on a surface of a sub-substrate on which a conductive land is formed. The sub-substrate is bonded to a main substrate.